



DDR4 DIMM

TE Internal #: 2199154-2

DIMM Sockets, Double Data Rate (DDR) 4, Board-to-Board, 288

Position, Through Hole - Solder Mount, Vertical Module

Orientation, DDR4 DIMM

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR4 DIMM SOCKETS



DRAM Type: **Double Data Rate (DDR) 4**

Connector System: **Board-to-Board**

Number of Positions: **288**

PCB Mounting Style: **Through Hole - Solder**

Module Orientation: **Vertical**

[All DDR4 DIMM SOCKETS \(69\)](#)

Features

Product Type Features

DRAM Type	Double Data Rate (DDR) 4
Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Number of Positions	288
Module Orientation	Vertical

Electrical Characteristics

DRAM Voltage	1.2 V
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Body Features

PCB Retention Feature Material	Stainless Steel
Ejector Material Color	Natural
Ejector Material	High Temperature Thermoplastic
Latch Color	Black



Ejector Location	Both Ends
Latch Material	High Temperature Thermoplastic
Retention Post Location	None
Module Key Type	Offset Right
Ejector Type	Standard

Contact Features

Memory Socket Type	Memory Card
Socket Style	DIMM
PCB Contact Termination Area Plating Material Thickness	3 μm [118.1 μin]
Contact Mating Area Plating Material Thickness	.76 μm [30 μin]
Contact Mating Area Plating Material	Gold
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.75 A

Termination Features

Insertion Style	Direct Insert
Termination Post & Tail Length	2.67 mm[.105 in]

Mechanical Attachment

Mating Alignment Type	Offset Right
Mating Alignment	With
Mount Angle	Vertical
PCB Mount Retention	With
PCB Mount Retention Type	Boardlock
PCB Mounting Style	Through Hole - Solder
Connector Mounting Type	Board Mount

Housing Features

Housing Material	High Temperature Nylon
Housing Color	Black
Centerline (Pitch)	.85 mm[.033 in]

Dimensions

Center Retention Hole Diameter	1.2 mm[.047 in]
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Profile Height from PCB	20 mm[.787 in]
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Row-to-Row Spacing	2.2 mm[.08 in]
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Usage Conditions

Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	80
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Packaging Method	Box & Tray, Tray
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Not Yet Reviewed
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUL 2019 (201) Does not contain REACH SVHC
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Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
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Solder Process Capability	Wave solder capable to 260°C
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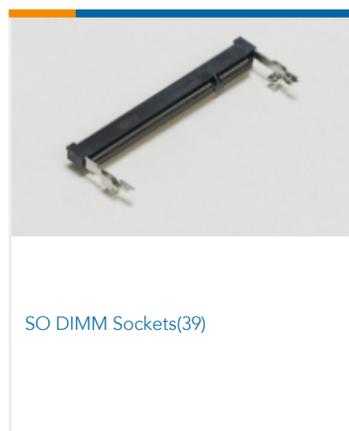
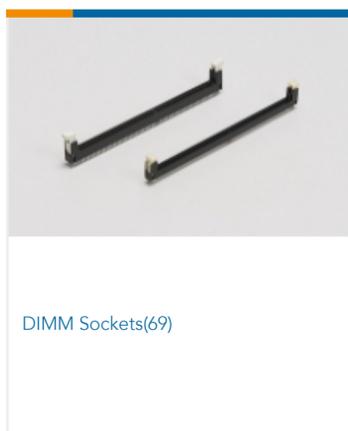
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | DDR4 DIMM



Documents

Product Drawings

DDR4 DIMM 288 Pin TH type

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_2199154-2_C4.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2199154-2_C4.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2199154-2_C4.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

DDR4 DIMM Socket Flyer (English)

English

DDR4 DIMM Socket Flyer (Chinese)



Product Specifications

Product Specification

English

Product Specification

English